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SPECIFICATION

CUSTOMER ： _____

MODULE NO.: WF57BTIACD0#

APPROVED BY: **(FOR CUSTOMER USE ONLY)**	**PCB VERSION:** **DATA:**

SALES BY	APPROVED BY	CHECKED BY	PREPARED BY

VERSION	DATE	REVISED PAGE NO.	SUMMARY
A	2008.10.07	24	Add FPC pitch.

Winstar Display Co., LTD
華凌光電股份有限公司

MODLE NO：

RECORDS OF REVISION

DOC. FIRST ISSUE

VERSION	DATE	REVISED PAGE NO.	**SUMMARY**
0	2008.04.01		First issue
A	2008.10.07	24	Add FPC pitch.

Contents

1.Module Classification Information

W F 57 B T I A C D 0 #
① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨⑩ ⑪

① Brand：WINSTAR DISPLAY CORPORATION
② Display Type：H→Character Type, G→Graphic Type F→TFT Type
③ Display Size：5.7” TFT
④ Model serials no.
⑤ Backlight Type： F→CCFL, White T→LED, White

⑥ LCD Polarize Type/ Temperature range/ View direction

A→Reflective, N.T, 6:00	H→Transflective, W.T,6:00
D→Reflective, N.T, 12:00	K→Transflective, W.T,12:00
G→Reflective, W. T, 6:00	C→Transmissive, N.T,6:00
J→Reflective, W. T, 12:00	F→Transmissive, N.T,12:00
B→Transflective, N.T,6:00	I→Transmissive, W. T, 6:00
E→Transflective, N.T.12:00	L→Transmissive, W.T,12:00

⑦ A: TFT LCD
B: TFT+FR+CONTROL BOARD
C: TFT+FR+A/D BOARD
D:TFT+FR+A/D BOARD+CONTROL BOARD

⑧ Solution: A: 128160 B:320234 C:320240 D:480234

⑨ D: Digital A: Analog

⑩ Version

⑪ Special Code #:Fit in with ROHS directive regulations

SUMMARY

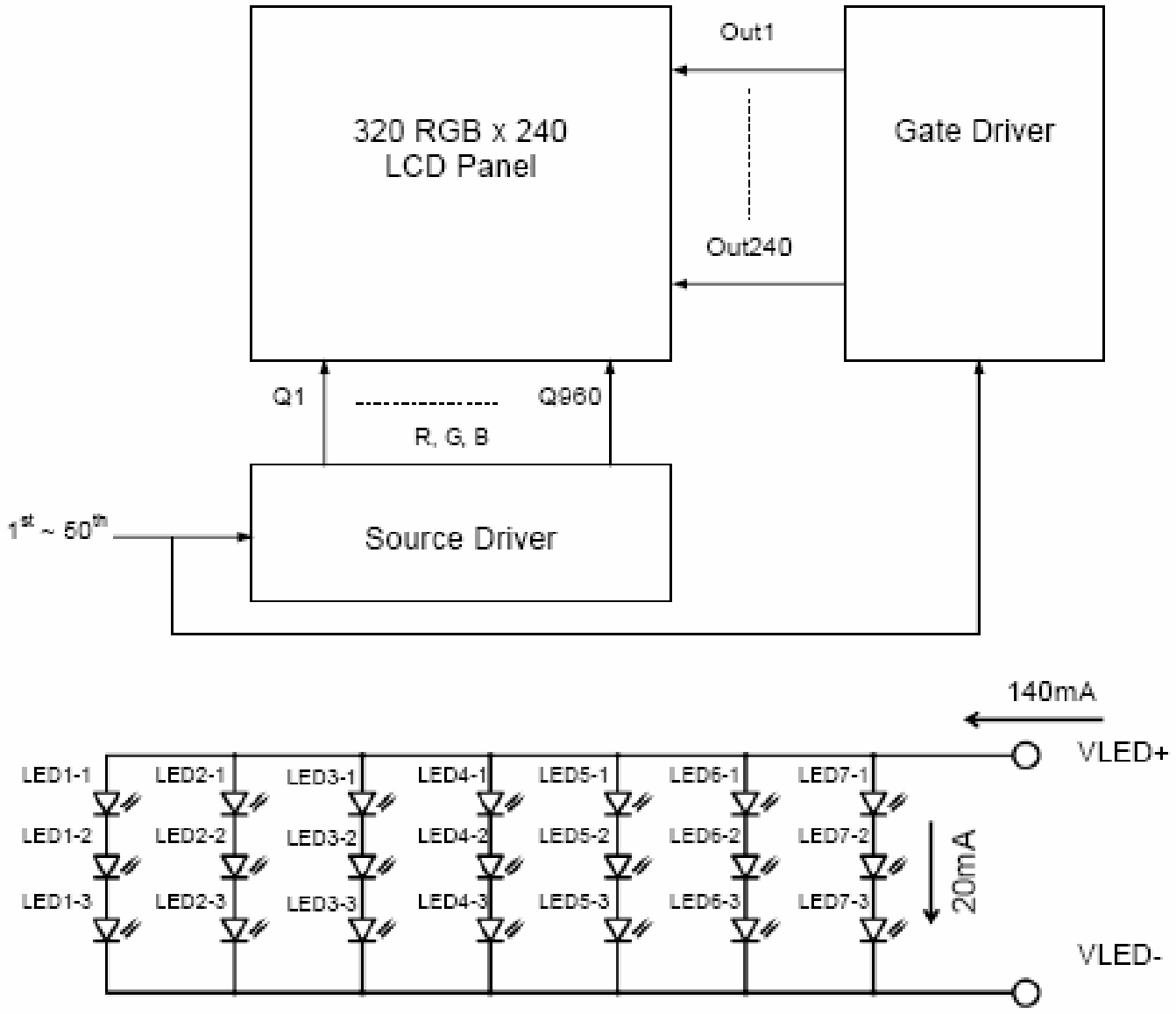
This technical specification applies to 5.7“ color TFT-LCD panel. The 5.7“ color TFT-LCD panel is designed for industry, vehicle application and other electronic products which require high quality flat panel displays. This module follows RoHS.

FEATURES

High Resolution: 230,400 Dots (320 RGB x 240). Image Reversion: Up/Down and Left/Right.

Item	Dimension	Unit
Dot Matrix	320 RGBx240(TFT)	dots
Module dimension	149.0x 109.0 x 9.9 (max)	mm
Active area	115.20x 86.4	mm
Dot pitch	0.12 x 0.36	mm
LCD type	TFT, Negative, Transmissive	
View direction	6 o’clock	
Backlight Type	LED,Normally White	

2.Block Diagram



3.Electrical Characteristics

Item	Symbol	Condition	Min	Typ	Max	Unit
Supply Voltage For Logic	V_{DD}	—	3.0	3.3	3.6	V
Input High Volt.	V_{IH}	—	0.7 V_{DD}	—	V_{DD}	V
Input Low Volt.	V_{IL}	—	0	—	0.3 V_{DD}	V
LCD Driving Supply Voltage	V_{GH} *1	Ta=25℃		15		V *3
	V_{GL}*2			-10		
	VcomH		2.5		5.5	
	VcomL		-2.0		0	
Supply Current	I_{VDD}	V_{DD}=3.3V	—	5	8	mA

Notes:
*1) VGH is TFT Gate on operating Voltage.
*2) VGL is TFT Gate off operating Voltage, VGL signal must be fluctuates with same phase as Vcom when Storage on Gate structure.
*3) Vcom must be adjusted to optimize display quality_Crosstalk,Contrast Ratio and etc.

4.Absolute Maximum Ratings

Item	Symbol	Min	Typ	Max	Unit
Operating Temperature	T_{OP}	-20	—	+70	℃
Storage Temperature	T_{ST}	-30	—	+80	℃
Power Supply Voltage	V_{GH}	-0.3	—	32.0	V
	V_{GL}	-22	—	0.3	V
	V_{GH} - V_{GL}	-0.3	—	+45	V

5.Interface Pin Function

5-1 LCM PIN Definition

Pin No.	Symbol	I/O	Description	Remark
1	IF1	I	Input data format control (Note1)	Note1
2	IF2	I	Input data format control (Note1)	Note1
3	POL	O	Polarity Signal connect to VCOM driving circuit.	Note3
4	RESET	I	Hardware reset.	
5	SPENA	I	Chip select	Note2
6	SPCL	I	Serial Clock	Note2
7	SPDA	I/O	Serial Data	
8	B0	I	Blue Data bit (LSB)	
9	B1	I	Blue Data bit	
10	B2	I	Blue Data bit	
11	B3	I	Blue Data bit	
12	B4	I	Blue Data bit	
13	B5	I	Blue Data bit	
14	B6	I	Blue Data bit	
15	B7	I	Blue Data bit(MSB)	
16	G0	I	Green Data bit(LSB)	
17	G1	I	Green Data bit	
18	G2	I	Green Data bit	
19	G3	I	Green Data bit	
20	G4	I	Green Data bit	
21	G5	I	Green Data bit	
22	G6	I	Green Data bit	
23	G7	I	Green Data bit(MSB)	
24	R0	I	Red Data bit(LSB)	
25	R1	I	Red Data bit	
26	R2	I	Red Data bit	
27	R3	I	Red Data bit	
28	R4	I	Red Data bit	
29	R5	I	Red Data bit	
30	R6	I	Red Data bit	
31	R7	I	Red Data bit(MSB)	
32	Hsync	I	Horizontal synchronous signal	
33	Vsync	I	Vertical synchronous signal	
34	Data CLK	I	Dot data clock	
35	AVDD(analog)	I	Analog power: 4.5V~5.5V	
36	AVDD(analog)	I	Analog power: 4.5V~5.5V	
37	VDD(Digital)	I	Digital power: 3V~3.6V	
38	VDD(Digital)	I	Digital power: 3V~3.6V	
39	NPC	O	NTSC/PAL mode Auto detection result H:NTSC/L:PAL	
40	VGL	I	Gate off power	
41	VGL	I	Gate off power	
42	UD	I	Up/Down scan setting. H: Reverse scan / L: Normal scan	
43	VGH	I	Gate on power	

44	LRC	I	Shift direction of device internal shift register control.	
45	GND	I	GROUND	
46	VCOM	I	VCOM driving input	Note3
47	VCOM	I	VCOM driving input	
48	ENB	I	Data enable input. Normally pull low.	Note4
49	GND	I	GROUND	
50	GND	I	GROUND	

Note: 1.Control the input data format.

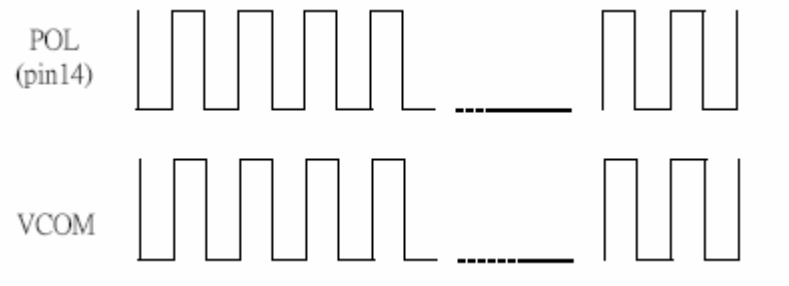
IF2,IF1	Input data format
L,L(default)	Serial RGB
L,H	Parallel RGB
H,L	CCIR601
H,H	CCIR656

2. Pin 5、Pin 6 usually pull high.

3. The polarity of VCOM (Pin 46,47) should be generated from POL (Pin 3).

4. For digital RGB input data format, both SYNC mode and DE+SYNC mode are supported. If ENB signal is fixed low, SYNC mode is used. Otherwise, DE+SYNC mode is used.

5. The phase of POL (pin 3):



5.2 Backlight PIN Definition

Pin No.	Symbol	I/O	Description
1	VLED+	I	Red, LED_ Anode
2	VLED-	I	White, LED_ Cathode

Note: The backlight interface connector is a model **PHR-2** manufactured by JST or equivalent.

The matching connector part number is **S 2B-PH-K-S** manufactured by JST or equivalent.

6. AC Characteristics

6.1. CCIR601/656 Interface

6.1.1. Input signal characteristics

PARAMETER	Symbol	Min.	Typ.	Max.	Unit
CLK period	T_{OSC}	-	37	-	ns
Data setup time	T_{SU}	12	-	-	ns
Data hold time	T_{HD}	12	-	-	ns

6.1.2 Hardware reset timing

PARAMETER	Symbol	Min.	Typ.	Max.	Unit
RESET low pulse width	T_{RSB}	10	-	-	μs

6.1.3. Output signal characteristics

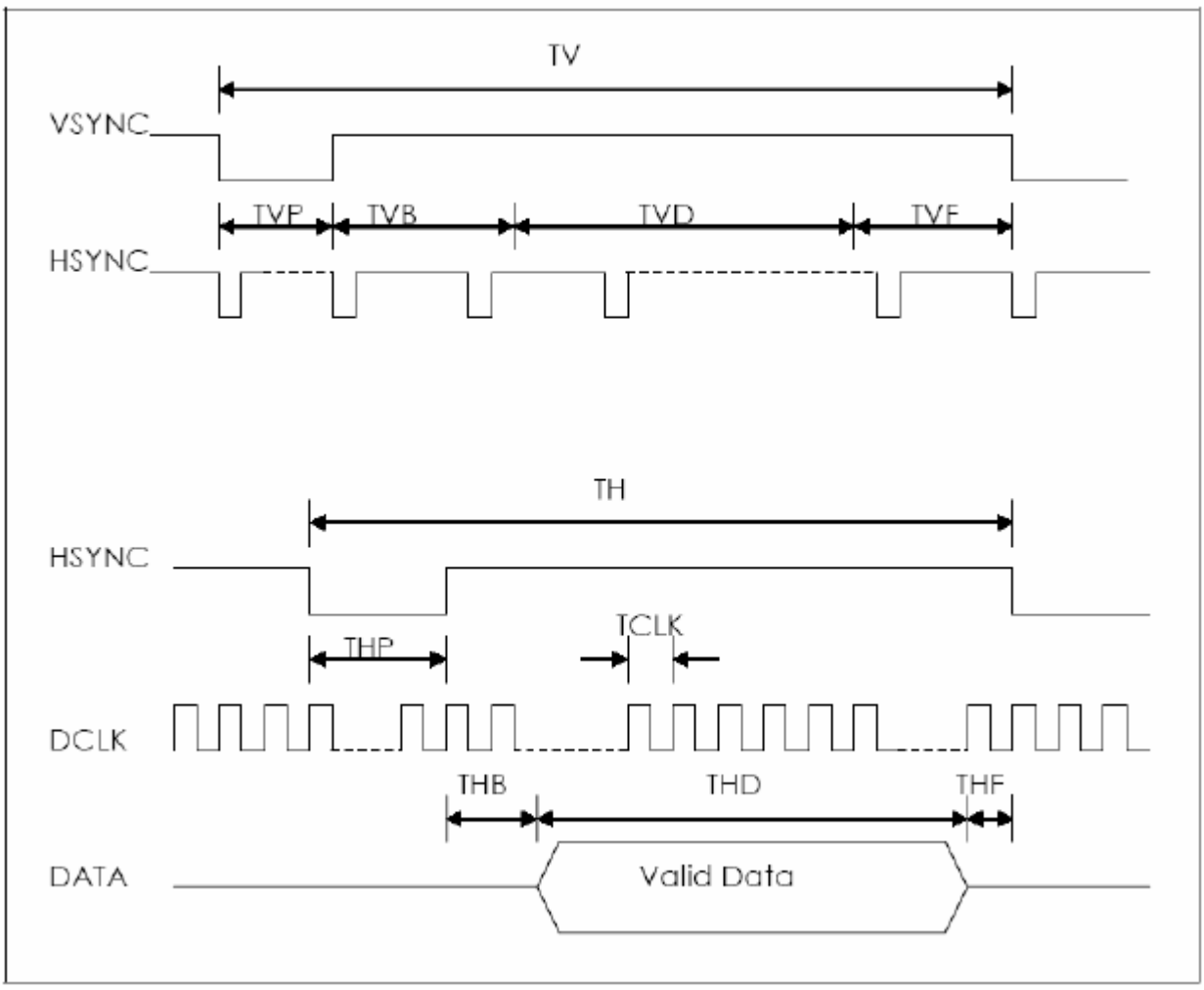
PARAMETER		Symbol	Min.	Typ.	Max.	Unit
Rising time		T_r	-	-	10	ns
Falling time		T_f	-	-	10	ns
Internal STH setup time		T_{SUS}	12	-	-	ns
Internal STH hold time		T_{HDS}	12	-	-	ns
Internal data setup time		T_{SUD}	60	-	-	ns
Internal data hold time		T_{HDD}	40	-	-	ns
OEH pulse width		T_{OEH}	-	1248	-	ns
OEV pulse width		T_{OEV}	-	4992	-	ns
CKV pulse width		T_{CKV}	-	3744	-	ns
Hsync – DEH time		T_1	-	4368	-	ns
Hsync – CKV time		T_2	-	2496	-	ns
Hsync – OEV time		T_3	-	624	-	ns
Vsync – setup time		T_{SUV}		1872	-	ns
Vsync – pulse time		T_{STV}		1	-	T_H
Vsync – STV time	NTSC	T_{VS1}	-	19	-	T_H
	PAL	T_{VS1}	-	27	-	T_H
OEH – STV time		T_{HE}	-	2	-	T_H
Output settling time		T_{OES}	-	12	20	μs

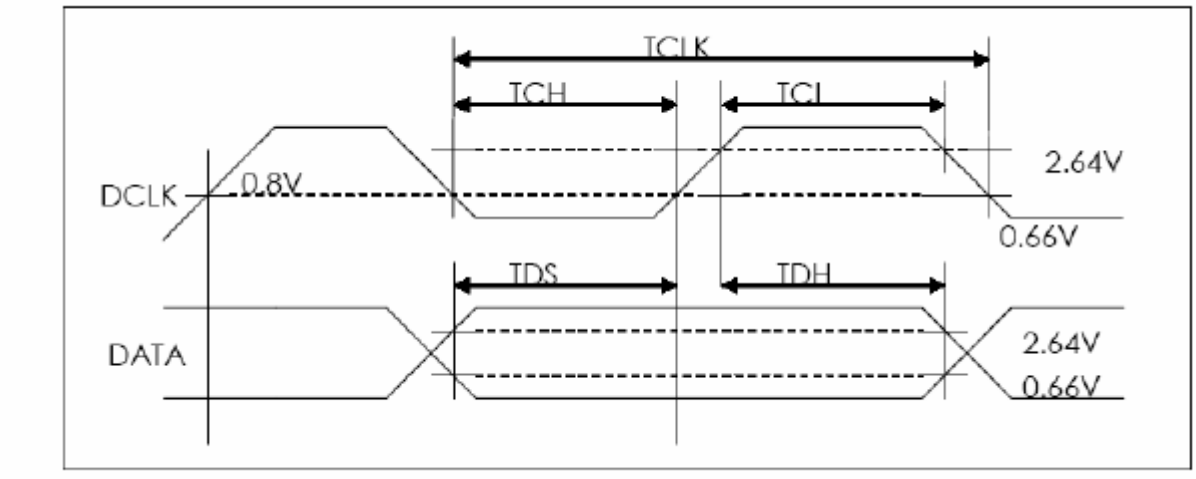
6.2. 24-bits parallel RGB Interface

6.2.1 AC Timing Characteristics

Signal	Item		Symbol	Min	Typ	Max	Unit
Dclk	Frequency		Dclk	-	6.4	-	MHZ
	High Time		Tch	-	78	-	ns
	Low Time		Tcl	-	78	-	ns
Data	Setup Time		Tds	12	-	-	ns
	Hold Time		Tdh	12	-	-	ns
Hsync	Period		TH	-	408	-	DCLK
	Pulse Width		Thp	-	30	-	DCLK
	Back-Porch		Thb	-	38	-	DCLK
	Display Period		Thd	-	320	-	DCLK
	Front-Porch		Thf	-	20	-	DCLK
Vsync	Period	NTSC	Tv	-	262.5	-	TH
		PAL			312.5		
	Pulse Width		Tvp	1	3	5	TH
	Back-Porch	NTSC	Tvb	-	15	-	TH
		PAL			23		
	Display Period		Tvd	-	240	-	TH
	Front-Porch	NTSC	Tvf	-	4.5	-	TH
		PAL			46.5		

6.2.2 AC Timing Diagrams

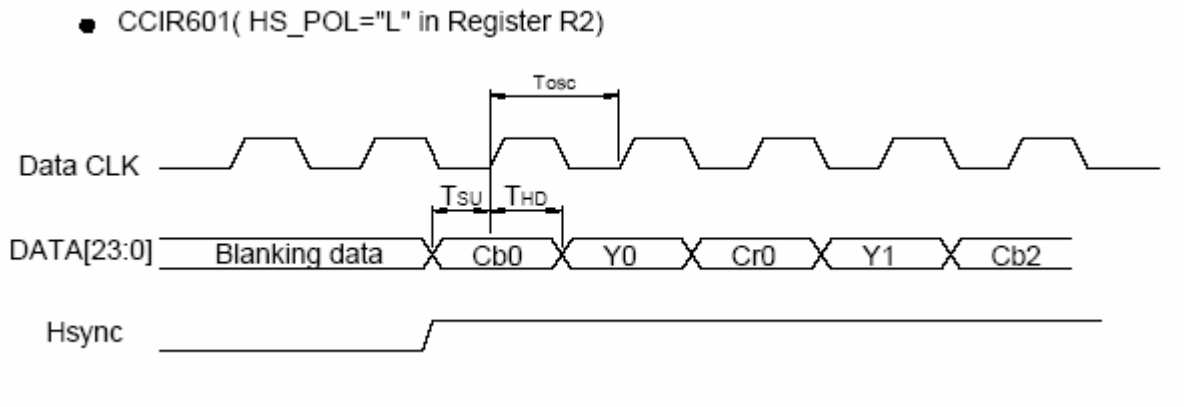


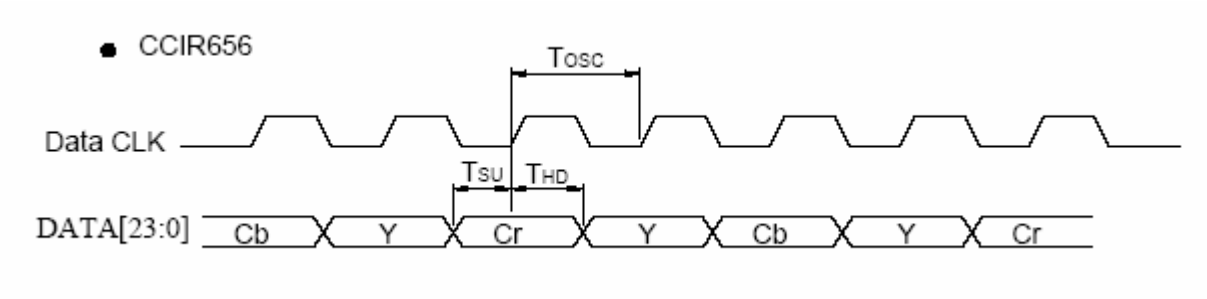


7. Waveform

7.1. Timing Controller Timing Chart

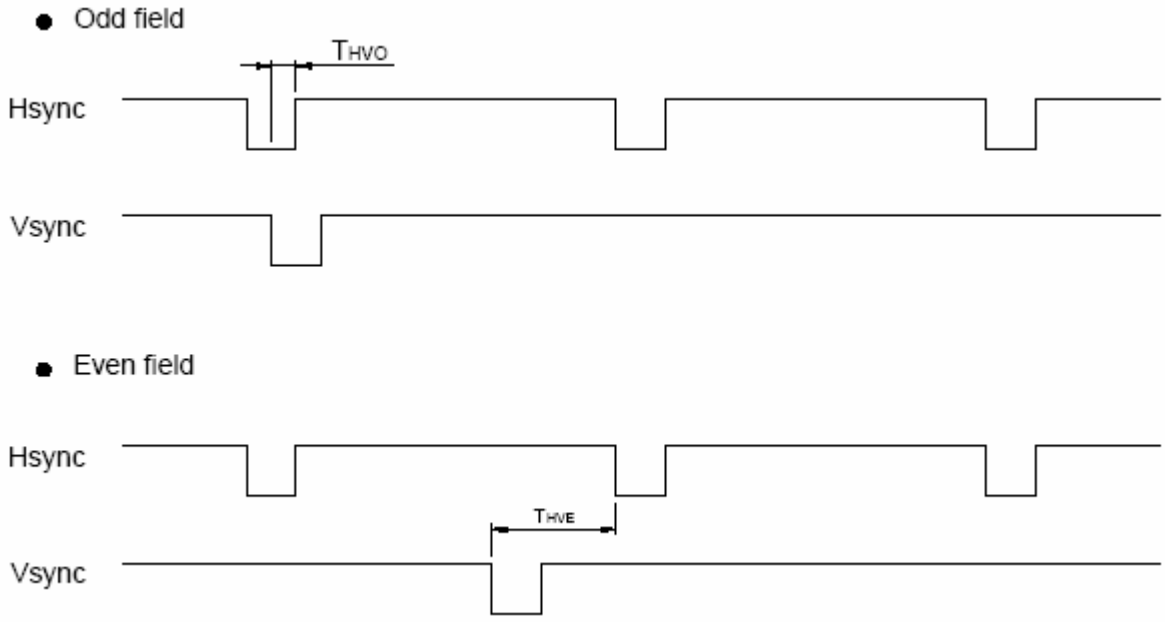
7.1.1. Clock and Data waveform



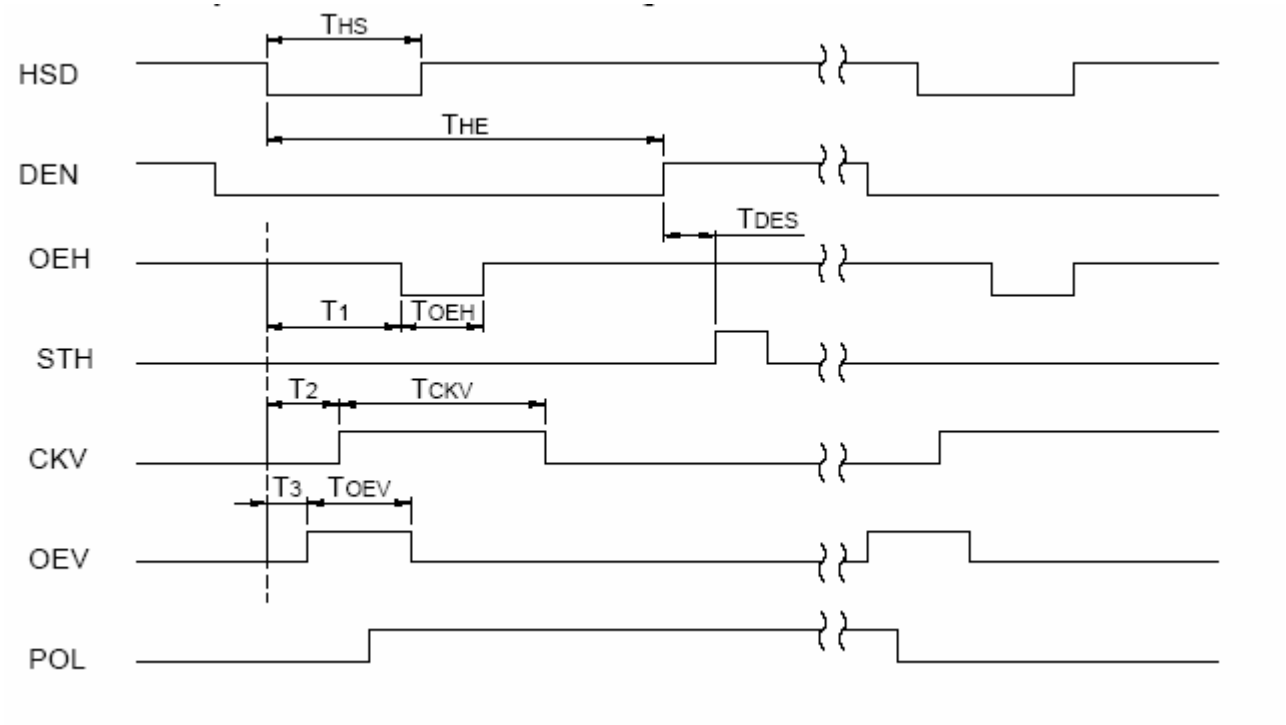


7.1.2 Digital / Analog RGB timing waveform

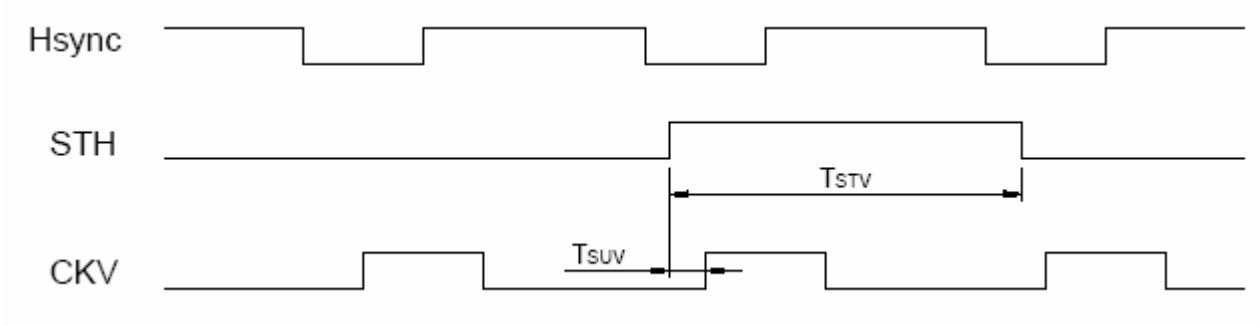
7.1.2.1 Hsync and Vsync timing



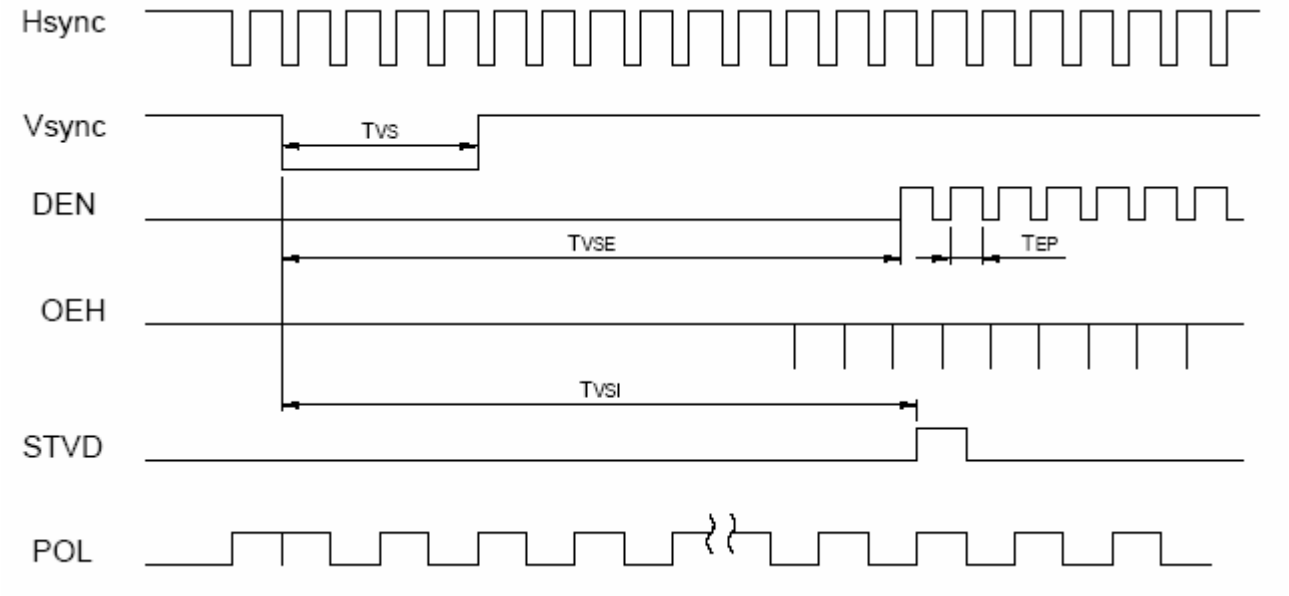
7.1.2.2 Hsync and horizontal control timing waveform



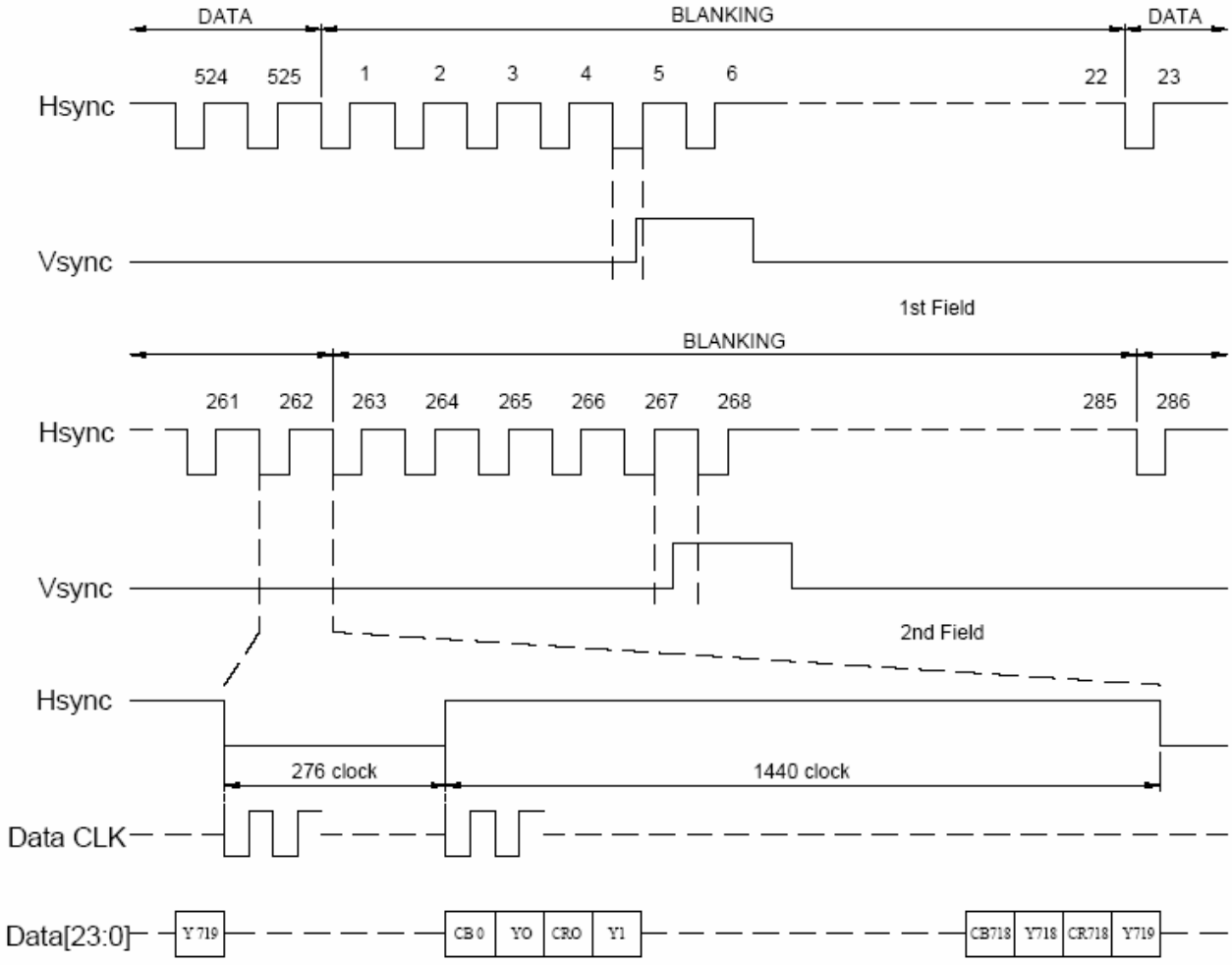
7.1.2.3 Hsync and vertical shift clock timing waveform



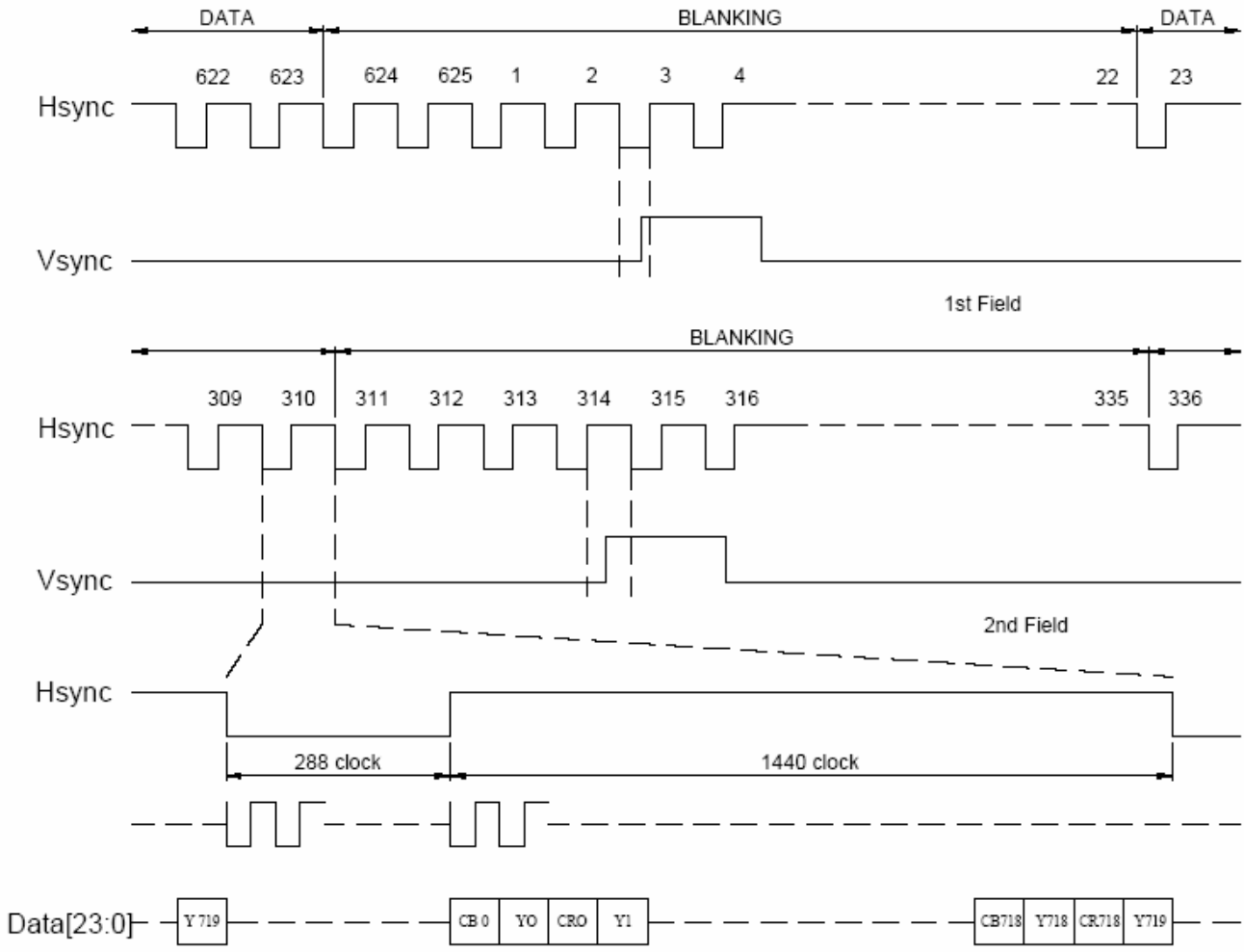
7.1.2.4 Hsync and vertical shift clock timing waveform



7.1.3 CCIR601 timing waveform (VS_POL="H" , HS_POL="L" in Register R2)



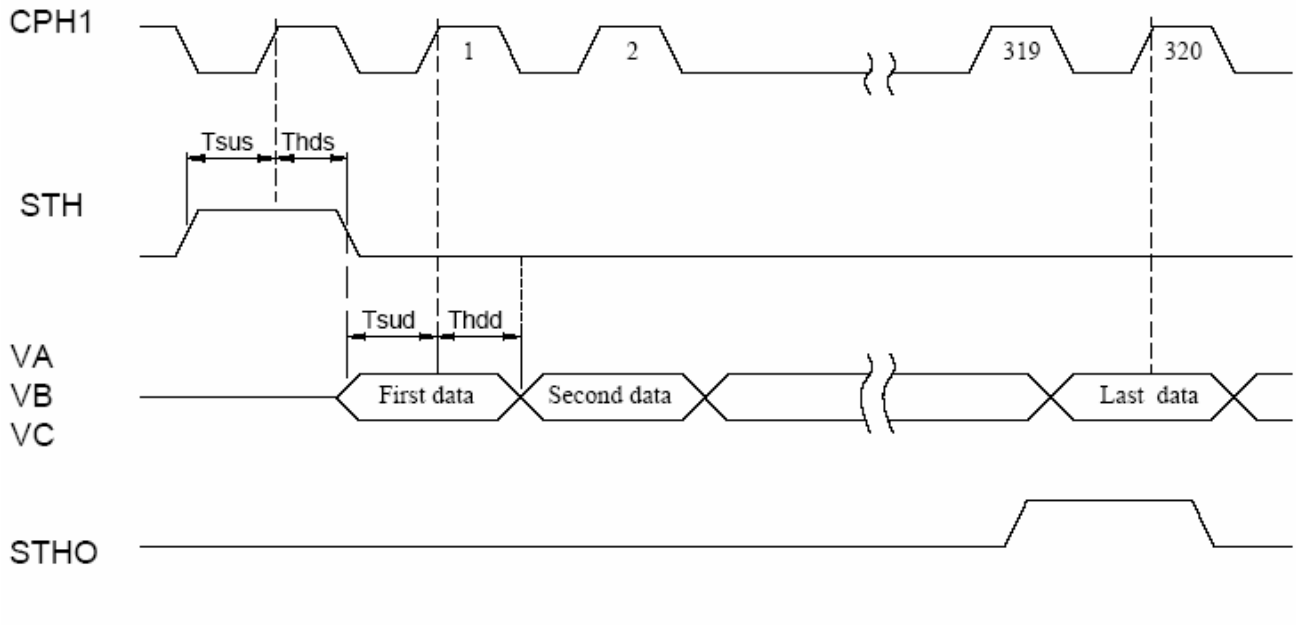
ITU-BT.601 NTSC Input Timing



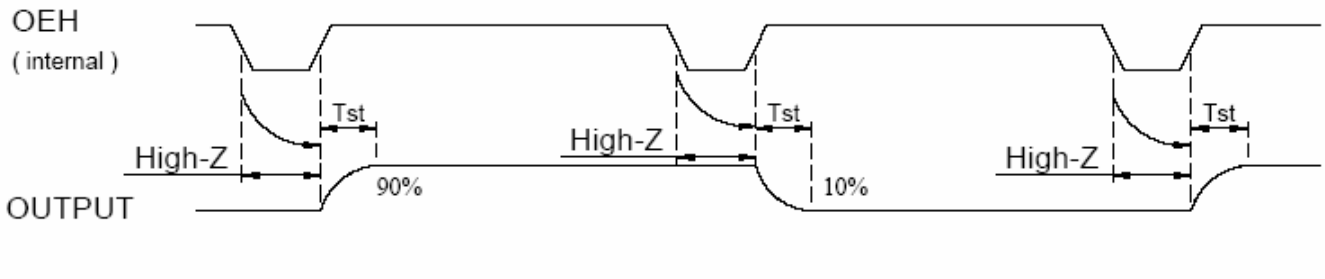
ITU-BT.601 PAL Input Timing

7.2 Source Driver Timing Chart

7.2.1 Clock and Start Pulse timing waveform



7.2.2 OEH and Data Output timing waveform



7.3 Analog video signal characteristics

PARAMETER	Symbol	Min.	Typ.	Max.	Unit
Video signal amplitude (VA, VB, VC)	V_{IAC}	-	3.81	-	V
	V_{IDC}	-	2.385	-	V

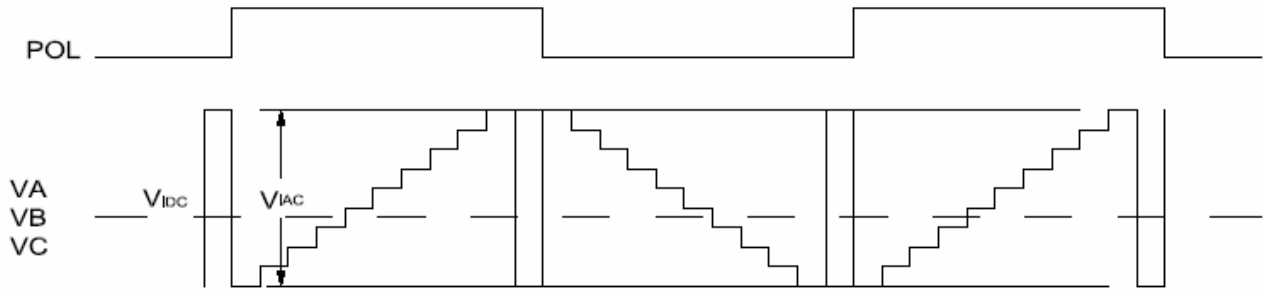
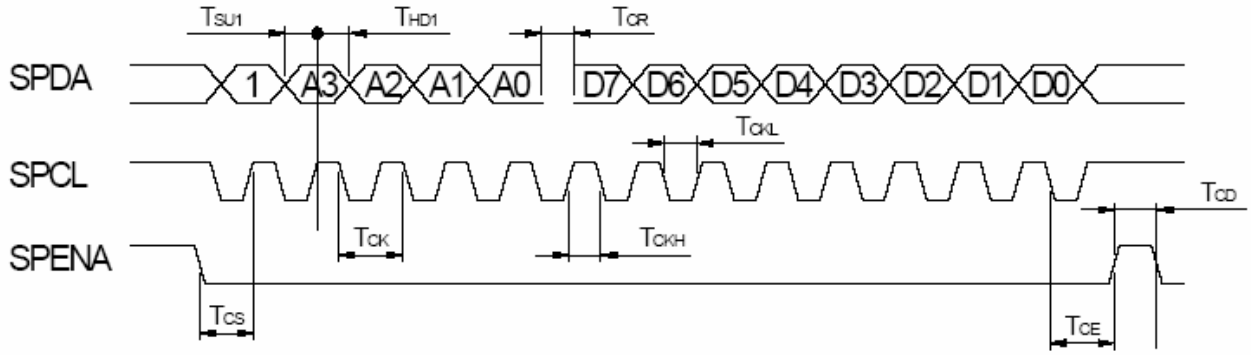


Fig. 4-(a) Horizontal timing

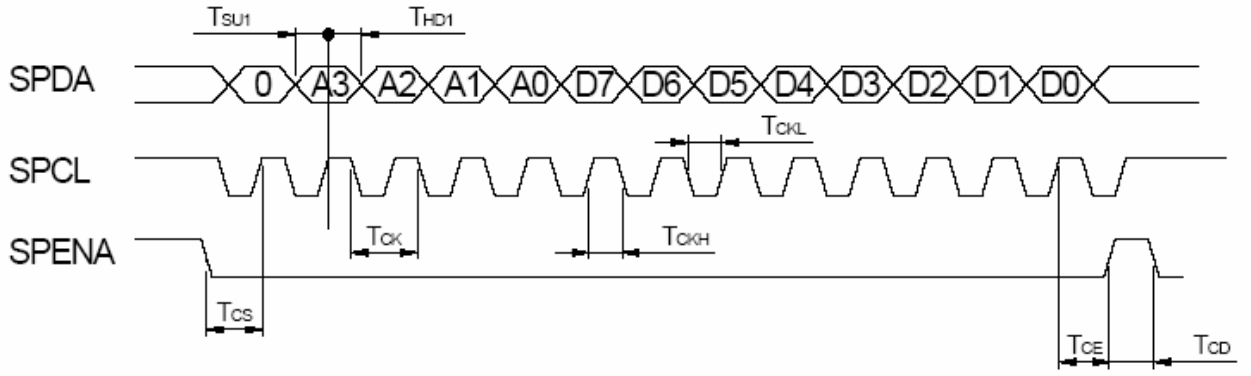
7.4 SPI timing characteristics

PARAMETER	Symbol	Min.	Typ.	Max.	Unit
SPCL period	T_{CK}	60	-	-	ns
SPCL high width	T_{CKH}	30	-	-	ns
SPCL low width	T_{CKL}	30	-	-	ns
Data setup time	T_{SU1}	12	-	-	ns
Data hold time	T_{HD1}	12	-	-	ns
SPENA to SPCK setup time	T_{CS}	20	-	-	ns
SPENA to SPDA hold time	T_{CE}	20	-	-	ns
SPENA high pulse width	T_{CD}	50	-	-	ns
SPDA output latency	T_{CR}		1/2	-	T_{CK}

- SPI "read" timing

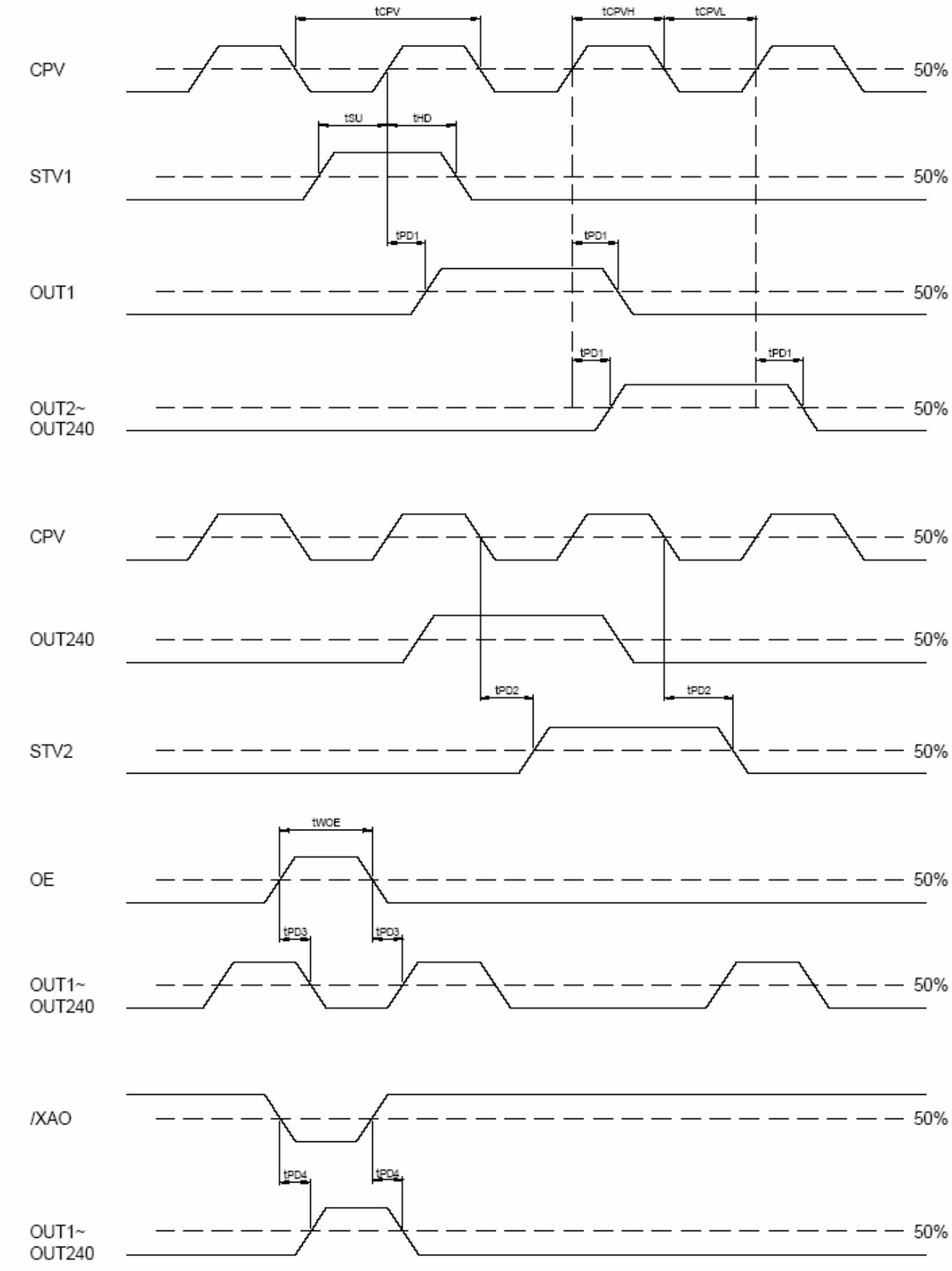


- SPI "write" timing



7.5 Gate Driver Timing Chart

Parameter	Symbol	Condition	Spec		Unit
			Min.	Max.	
Operation frequency	tCPV		5	-	μs
CPV pulse width	tCPVH,tCPVL	50%duty cycle	2.5	-	
OE pulse width	twOE		1	-	
Data setup time	tsu		0.4	-	us
Data hold time	thd		0.7	-	
Output delay time	tpd1	CL=300pF	-	1	
Output delay time	tpd2	CL=300pF	-	0.8	
Output delay time	tpd3	CL=300pF	-	0.8	
Output delay time	tpd4	CL=300pF	-	10	


tCPV
tCPVH
tCPVL
CPV
50%
tSU
tHD
STV1
50%
tPD1
tPD1
OUT1
50%
tPD1
tPD1
OUT2~
OUT240
50%
CPV
50%
OUT240
50%
tPD2
tPD2
STV2
50%
tWOE
OE
50%
tPD3
tPD3
OUT1~
OUT240
50%
/XAO
50%
tPD4
tPD4
OUT1~
OUT240
50%

8.Optical Characteristics

Ta=25±2℃, ILED=140mA

Item		Symbol	Condition	Min.	Typ.	Max.	Unit	Remark
Response time		Tr	θ=0°	-	15	30	ms	Note 3,5
		Tf		-	35	50	ms	
Contrast ratio		CR	At optimized viewing angle	150	200			Note 4,5
Color Chromaticity	White	Wx	θ=0°	(0.25)	(0.30)	(0.35)		Note 2,6,7
		Wy		(0.27)	(0.32)	(0.37)		
Viewing angle	Hor.	Θ_R	CR≥10	50	65	-	Deg.	Note 1
		Θ_L		50	65	-		
	Ver.	Θ_T		30	50	-		
		Θ_B		50	55	-		
Uniformity		U	-	(70)	(75)	-	%	Note 8
Brightness		-	-	300	350	-	cd/m^2	Center of display

Note 1: Definition of viewing angle range

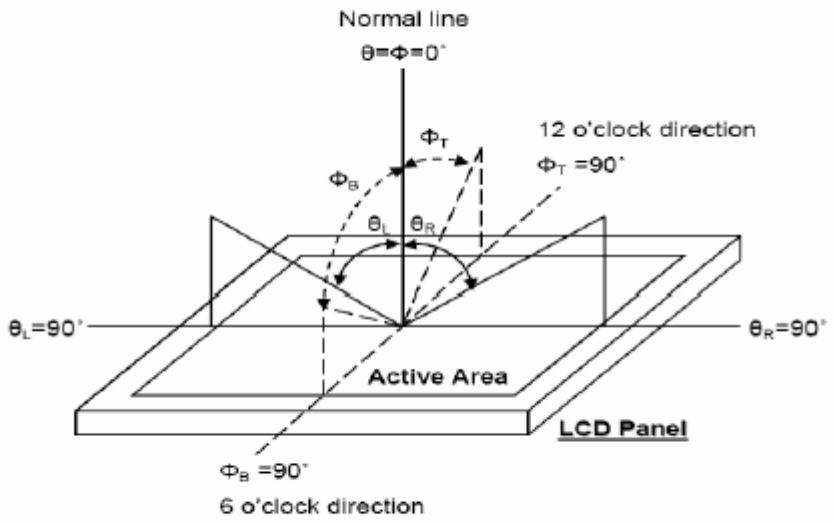


Fig. 8-1 Definition of viewing angle

Note 2: Test equipment setup:

After stabilizing and leaving the panel alone at a driven temperature for 5 minutes, the measurement should be executed. Measurement should be executed in a stable, windless, and dark room. Optical specifications are measured by Topcon BM-7 luminance meter 1.0° field of view at a distance of 50cm and normal direction.

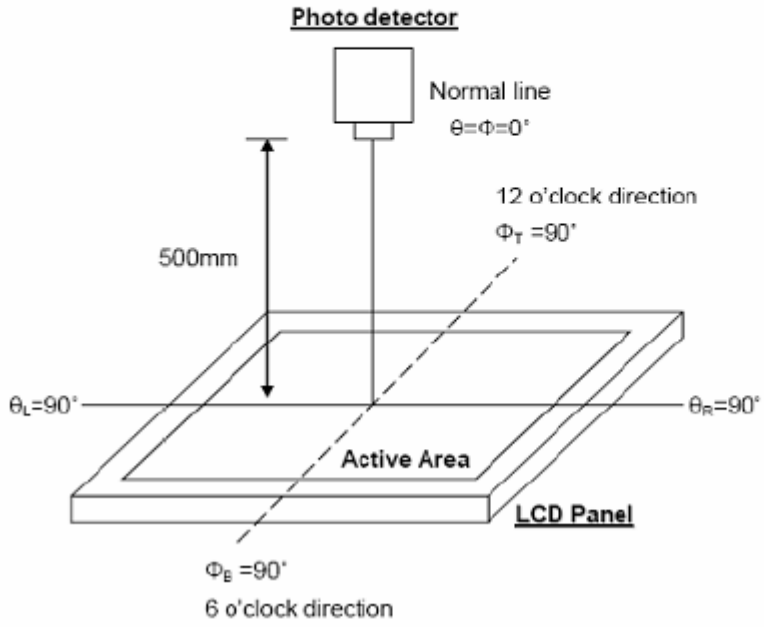


Fig. 8-2 Optical measurement system setup

Note 3: Definition of Response time:

The response time is defined as the LCD optical switching time interval between "White" state and "Black" state. Rise time, Tr, is the time between photo detector output intensity changed from 90% to 10% . And fall time, Tf, is the time between photo detector output intensity changed from 10% to 90% .

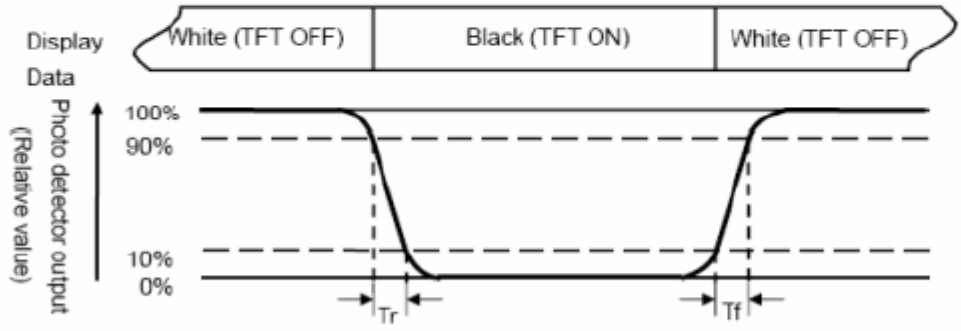


Fig. 3-3 Definition of response time

Note 4: Definition of contrast ratio:
The contrast ratio is defined as the following expression.

$$\text{Contrast ratio (CR)} = \frac{\text{Luminance measured when LCD on the “White” state}}{\text{Luminance measured when LCD on the “Black” state}}$$

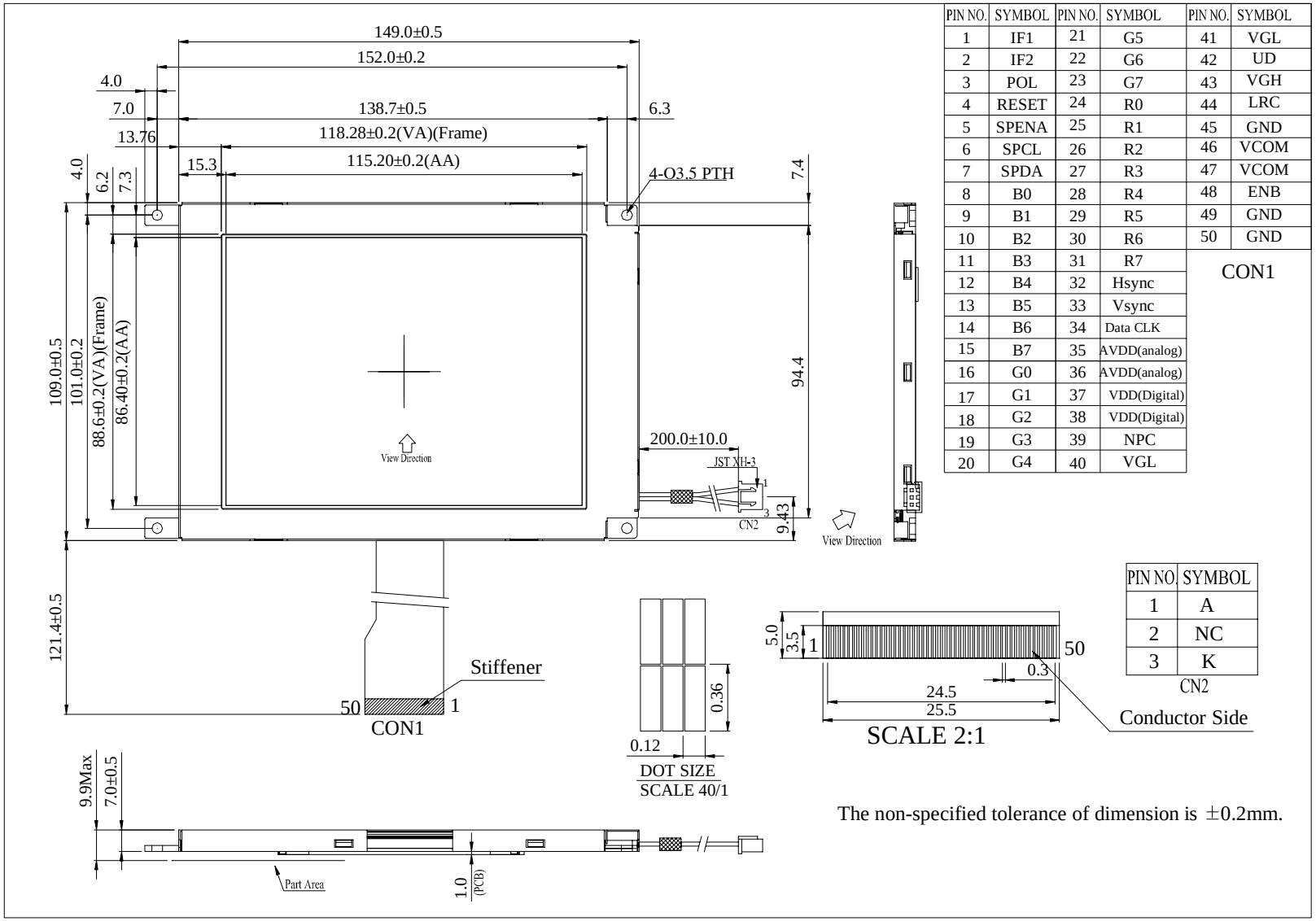
Note 5: White Vi = $V_{i50} \pm 1.5V$
Black Vi = $V_{i50} \pm 2.0V$
“±” means that the analog input signal swings in phase with VCOM signal.
“±” means that the analog input signal swings out of phase with VCOM signal.
The 100% transmission is defined as the transmission of LCD panel when all the input terminals of module are electrically opened.

Note 6: Definition of color chromaticity (CIE 1931)
Color coordinates measured at the center point of LCD

Note 7: Measured at the center area of the panel when all the input terminals of LCD panel are electrically opened.

$$\text{Note 8 : Uniformity (U)} = \frac{\text{Brightness (min)}}{\text{Brightness (max)}} \times 100\%$$

9.Contour Drawing



PIN NO.	SYMBOL	PIN NO.	SYMBOL	PIN NO.	SYMBOL
1	IF1	21	G5	41	VGL
2	IF2	22	G6	42	UD
3	POL	23	G7	43	VGH
4	RESET	24	R0	44	LRC
5	SPENA	25	R1	45	GND
6	SPCL	26	R2	46	VCOM
7	SPDA	27	R3	47	VCOM
8	B0	28	R4	48	ENB
9	B1	29	R5	49	GND
10	B2	30	R6	50	GND
11	B3	31	R7		
12	B4	32	Hsync		
13	B5	33	Vsync		
14	B6	34	Data CLK		
15	B7	35	AVDD(analog)		
16	G0	36	AVDD(analog)		
17	G1	37	VDD(Digital)		
18	G2	38	VDD(Digital)		
19	G3	39	NPC		
20	G4	40	VGL		

CON1

PIN NO.	SYMBOL
1	A
2	NC
3	K

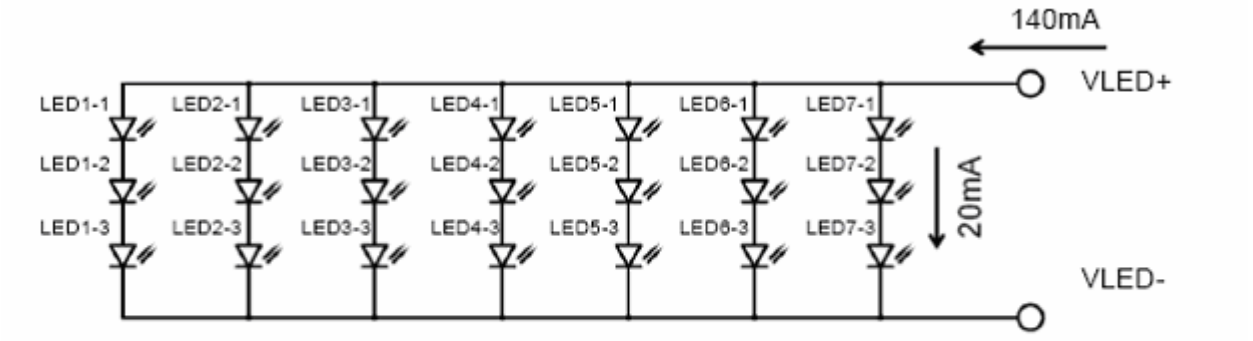
CN2

The non-specified tolerance of dimension is ±0.2mm.

10. LED driving conditions

Parameter	Symbol	Min.	Typ.	Max.	Unit	Remark
LED Current	I_{LED}	----	140	210	mA	Note1
LED voltage	V_{LED}	9.0	----	10.5	V	
LED life Time	-	(10,000)	----	----	-	Note 2,3
Luminous Intensity	IV	210.2	262.8	----	CD/M^2	Note 4

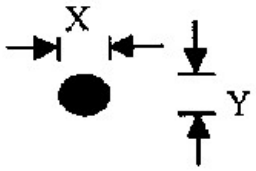
Note 1: There are 7 Groups LED shown as below, =9.9 V(Min)

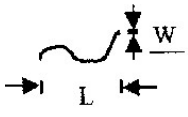


Note 2 : Ta = 25℃ ,
Note 3 : Brightess to be decreased to 50% of the initial value.

Note 4: The luminous is measured through LCD panel.

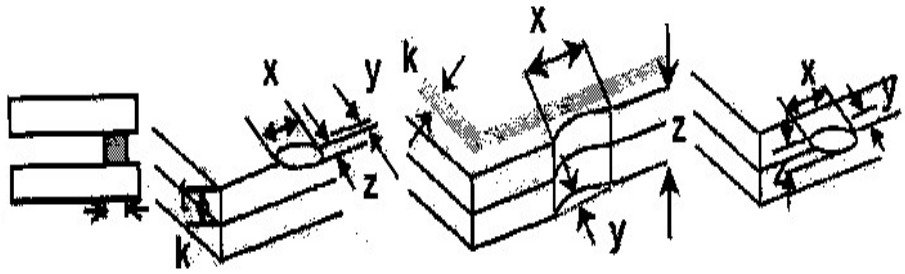
11. Inspection specification

<table>
<tr><th>NO</th><th>Item</th><th>Criterion</th><th>AQL</th></tr>
<tr><td>01</td><td>Electrical Testing</td><td>1.1 Missing vertical, horizontal segment, segment contrast defect.
1.2 Missing character , dot or icon.
1.3 Display malfunction.
1.4 No function or no display.
1.5 Current consumption exceeds product specifications.
1.6 LCD viewing angle defect.
1.7 Mixed product types.
1.8 Contrast defect.</td><td>0.65</td></tr>
<tr><td>02</td><td>Black or white spots on LCD (display only)</td><td>2.1 White and black spots on display ≦0.25mm, no more than three white or black spots present.
2.2 Densely spaced: No more than two spots or lines within 3mm</td><td>2.5</td></tr>
<tr><td rowspan="2">03</td><td rowspan="2">LCD black spots, white spots, contamination (non-display)</td><td>3.1 Round type : As following drawing
Φ=(x + y) / 2
 

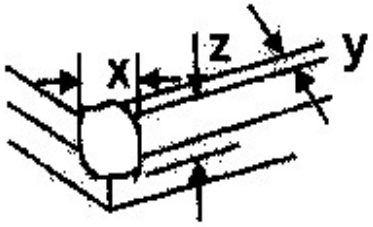
<table>
<tr><th>SIZE</th><th>Acceptable Q TY</th></tr>
<tr><td>Φ ≦0.10</td><td>Accept no dense</td></tr>
<tr><td>0.10＜Φ≦0.20</td><td>2</td></tr>
<tr><td>0.20＜Φ≦0.25</td><td>1</td></tr>
<tr><td>0.25＜Φ</td><td>0</td></tr>
</table></td><td>2.5</td></tr>
<tr><td>3.2 Line type : (As following drawing)
 

<table>
<tr><th>Length</th><th>Width</th><th>Acceptable Q TY</th></tr>
<tr><td>---</td><td>W≦0.02</td><td>Accept no dense</td></tr>
<tr><td>L≦3.0</td><td>0.02＜W≦0.03</td><td rowspan="2">2</td></tr>
<tr><td>L≦2.5</td><td>0.03＜W≦0.05</td></tr>
<tr><td>---</td><td>0.05＜W</td><td>As round type</td></tr>
</table></td><td>2.5</td></tr>
<tr><td>04</td><td>Polarizer bubbles</td><td>If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction.
<table>
<tr><th>Size Φ</th><th>Acceptable Q TY</th></tr>
<tr><td>Φ ≦0.20</td><td>Accept no dense</td></tr>
<tr><td>0.20＜Φ≦0.50</td><td>3</td></tr>
<tr><td>0.50＜Φ≦1.00</td><td>2</td></tr>
<tr><td>1.00＜Φ</td><td>0</td></tr>
<tr><td>Total Q TY</td><td>3</td></tr>
</table></td><td>2.5</td></tr>
</table>

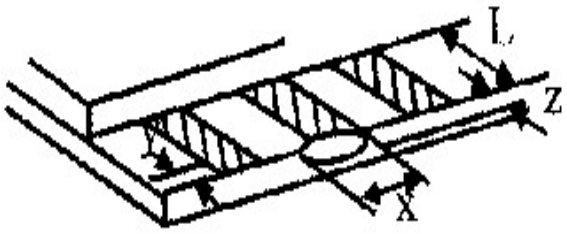
<table>
<tr><th>NO</th><th>Item</th><th>Criterion</th><th>AQL</th></tr>
<tr><td>05</td><td>Scratches</td><td>Follow NO.3 LCD black spots, white spots, contamination</td><td></td></tr>
<tr><td>06</td><td>Chipped glass</td><td>Symbols Define:
x: Chip length y: Chip width z: Chip thickness
k: Seal width t: Glass thickness a: LCD side length
L: Electrode pad length:

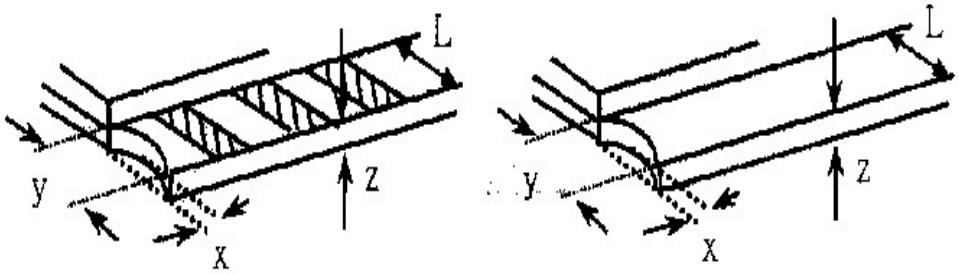
6.1 General glass chip :
6.1.1 Chip on panel surface and crack between panels:
 

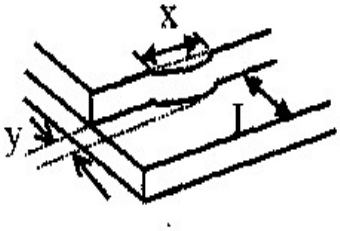
<table><tr><td>z: Chip thickness</td><td>y: Chip width</td><td>x: Chip length</td></tr><tr><td>Z≦1/2t</td><td>Not over viewing area</td><td>x≦1/8a</td></tr><tr><td>1/2t＜z≦2t</td><td>Not exceed 1/3k</td><td>x≦1/8a</td></tr></table>⊙If there are 2 or more chips, x is total length of each chip.

6.1.2 Corner crack:
 

<table><tr><td>z: Chip thickness</td><td>y: Chip width</td><td>x: Chip length</td></tr><tr><td>Z≦1/2t</td><td>Not over viewing area</td><td>x≦1/8a</td></tr><tr><td>1/2t＜z≦2t</td><td>Not exceed 1/3k</td><td>x≦1/8a</td></tr></table>⊙If there are 2 or more chips, x is the total length of each chip.</td><td>2.5</td></tr>
</table>

<table>
<tr><th>NO</th><th>Item</th><th>Criterion</th><th>AQL</th></tr>
<tr><td>06</td><td>Glass crack</td><td>
Symbols :
x: Chip length y: Chip width z: Chip thickness
k: Seal width t: Glass thickness a: LCD side length
L: Electrode pad length
6.2 Protrusion over terminal :
6.2.1 Chip on electrode pad :


<table>
<tr><td>y: Chip width</td><td>x: Chip length</td><td>z: Chip thickness</td></tr>
<tr><td>y≦0.5mm</td><td>x≦1/8a</td><td>0 ＜ z ≦ t</td></tr>
</table>
6.2.2 Non-conductive portion:


<table>
<tr><td>y: Chip width</td><td>x: Chip length</td><td>z: Chip thickness</td></tr>
<tr><td>y≦ L</td><td>x≦1/8a</td><td>0 ＜ z ≦ t</td></tr>
</table>
⊙If the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications.
⊙If the product will be heat sealed by the customer, the alignment mark not be damaged.
6.2.3 Substrate protuberance and internal crack.


<table>
<tr><td>y: width</td><td>x: length</td></tr>
<tr><td>y≦1/3L</td><td>x ≦ a</td></tr>
</table>
</td><td>2.5</td></tr>
</table>

NO	Item	Criterion	AQL
07	Cracked glass	The LCD with extensive crack is not acceptable.	2.5
08	Backlight elements	8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using LCD spot, lines and contamination standards. 8.3 Backlight doesn’ t light or color wrong.	0.65 2.5 0.65
09	Bezel	9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination. 9.2 Bezel must comply with job specifications.	2.5 0.65
10	PCB、COB	10.1 COB seal may not have pinholes larger than 0.2mm or contamination. 10.2 COB seal surface may not have pinholes through to the IC. 10.3 The height of the COB should not exceed the height indicated in the assembly diagram. 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places. 10.5 No oxidation or contamination PCB terminals. 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts. 10.7 The jumper on the PCB should conform to the product characteristic chart. 10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down.	2.5 2.5 0.65 2.5 2.5 0.65 0.65 2.5
11	Soldering	11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation or icicle. 11.3 No residue or solder balls on PCB. 11.4 No short circuits in components on PCB.	2.5 2.5 2.5 0.65

NO	Item	Criterion	AQL
12	General appearance	12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP. 12.2 No cracks on interface pin (OLB) of TCP. 12.3 No contamination, solder residue or solder balls on product. 12.4 The IC on the TCP may not be damaged, circuits. 12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it cause the interface pin to sever. 12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color. 12.7 Sealant on top of the ITO circuit has not hardened. 12.8 Pin type must match type in specification sheet. 12.9 LCD pin loose or missing pins. 12.10 Product packaging must the same as specified on packaging specification sheet. 12.11 Product dimension and structure must conform to product specification sheet.	2.5 0.65 2.5 2.5 2.5 2.5 2.5 0.65 0.65 0.65 0.65

winstar **LCM Sample Estimate Feedback Sheet**

Module Number： _____ **Page: 1**

1、Panel Specification：

1. Panel Type： ☐ Pass ☐ NG ,_____
2. View Direction： ☐ Pass ☐ NG ,_____
3. Numbers of Dots： ☐ Pass ☐ NG ,_____
4. View Area： ☐ Pass ☐ NG ,_____
5. Active Area： ☐ Pass ☐ NG ,_____
6. Operating Temperature： ☐ Pass ☐ NG ,_____
7. Storage Temperature： ☐ Pass ☐ NG ,_____
8. Others：_____

2、Mechanical Specification：

1. PCB Size： ☐ Pass ☐ NG ,_____
2. Frame Size： ☐ Pass ☐ NG ,_____
3. Material of Frame： ☐ Pass ☐ NG ,_____
4. Connector Position： ☐ Pass ☐ NG ,_____
5. Fix Hole Position： ☐ Pass ☐ NG ,_____
6. Backlight Position： ☐ Pass ☐ NG ,_____
7. Thickness of PCB： ☐ Pass ☐ NG ,_____
8. Height of Frame to PCB： ☐ Pass ☐ NG ,_____
9. Height of Module： ☐ Pass ☐ NG ,_____
10. Others： ☐ Pass ☐ NG ,_____

3、Relative Hole Size：

1. Pitch of Connector： ☐ Pass ☐ NG ,_____
2. Hole size of Connector： ☐ Pass ☐ NG ,_____
3. Mounting Hole size： ☐ Pass ☐ NG ,_____
4. Mounting Hole Type： ☐ Pass ☐ NG ,_____
5. Others： ☐ Pass ☐ NG ,_____

4、Backlight Specification：

1. B/L Type： ☐ Pass ☐ NG ,_____
2. B/L Color： ☐ Pass ☐ NG ,_____
3. B/L Driving Voltage (Reference for LED Type)： ☐ Pass ☐ NG ,_____
4. B/L Driving Current： ☐ Pass ☐ NG ,_____
5. Brightness of B/L： ☐ Pass ☐ NG ,_____
6. B/L Solder Method： ☐ Pass ☐ NG ,_____
7. Others： ☐ Pass ☐ NG ,_____

>> **Go to page 2** <<

5、Electronic Characteristics of Module：

1.	Input Voltage：	☐ Pass	☐ NG , _____
2.	Supply Current：	☐ Pass	☐ NG , _____
3.	Driving Voltage for LCD：	☐ Pass	☐ NG , _____
4.	Contrast for LCD：	☐ Pass	☐ NG , _____
5.	B/L Driving Method：	☐ Pass	☐ NG , _____
6.	Negative Voltage Output：	☐ Pass	☐ NG , _____
7.	Interface Function：	☐ Pass	☐ NG , _____
8.	LCD Uniformity：	☐ Pass	☐ NG , _____
9.	ESD test：	☐ Pass	☐ NG , _____
10.	Others：	☐ Pass	☐ NG , _____

6、Summary：

Sales signature：_____

Customer Signature：_____ **Date**：____/____/____